

Electronic Device Heatsink

This heatsink is designed for efficient heat dissipation in electronic devices. It features a dense array of cylindrical fins to maximize surface area for optimal thermal conductivity.



Overview

High-Performance Thermal Management

This high-performance heatsink is engineered for efficient heat dissipation in critical electronic devices. Featuring a dense array of cylindrical fins, the design maximizes surface area to ensure optimal thermal conductivity and performance. It is an ideal solution for cooling CPUs, GPUs, and other heat-generating components, providing reliable protection against overheating.

Technical Specifications

Design Features

- Dense cylindrical fin array
- High surface area design
- Optimized for thermal conductivity

Compatible Applications

CPU Cooling, GPU Cooling, Electronic Systems, General Electronics

Material & Construction

Material Composition

Aluminum Alloy • Copper Alloy